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WORLD INTELLECTUAL PROPERTY ORGANIZATION
International Bureau

9900328-7
IPOS

INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification 6 :
B24D 3/00, 11/02

A1

(11) International Publication Number: WO 98/06541

(43) International Publication Date: 19 February 1998 (19.02.98)

(21) International Application Number: PCT/US97/13047

(22) International Filing Date: 6 August 1997 (06.08.97)

(30) Priority Data:
08/694,357 8 August 1996 (08.08.96) US

(71) Applicant: MINNESOTA MINING AND MANUFACTURING COMPANY [US/US]; 3M Center, P.O. Box 33427, Saint Paul, MN 55133-3427 (US).

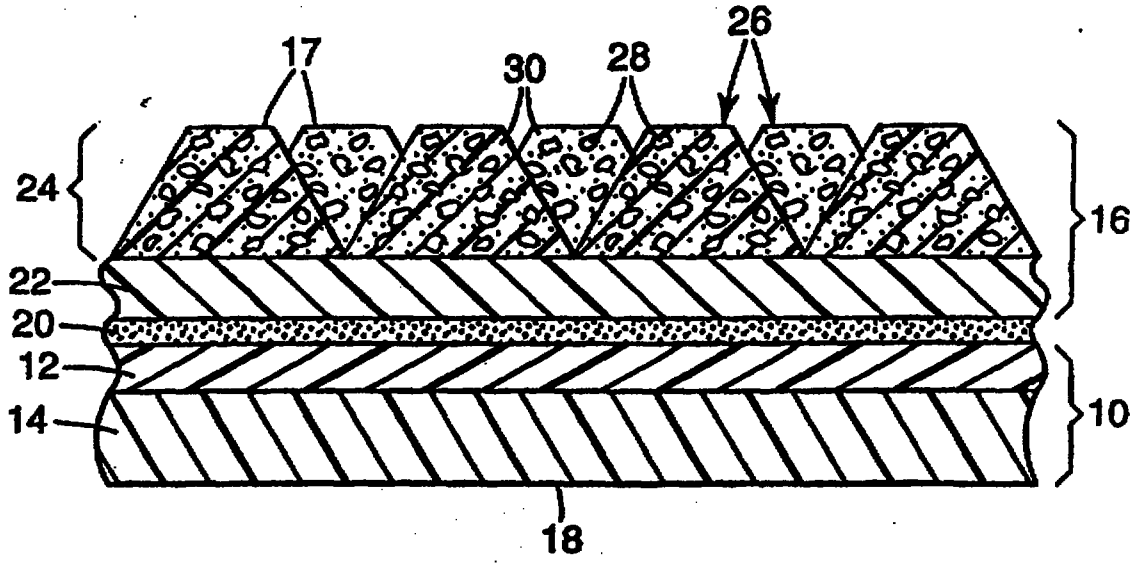
(72) Inventors: RUTHERFORD, Denise, R.; P.O. Box 33427, Saint Paul, MN 55133-3427 (US). GOETZ, Douglas, P.; P.O. Box 33427, Saint Paul, MN 55133-3427 (US). THOMAS, Cristina, U.; P.O. Box 33427, Saint Paul, MN 55133-3427 (US). WEBB, Richard, J.; P.O. Box 33427, Saint Paul, MN 55133-3427 (US). BRUXVOORT, Wesley, J.; P.O. Box 33427, Saint Paul, MN 55133-3427 (US). BUHLER, James, D.; P.O. Box 33427, Saint Paul, MN 55133-3427 (US). HOLLYWOOD, William, J.; P.O. Box 33427, Saint Paul, MN 55133-3427 (US).

(74) Agents: BUSSE, Paul, W. et al.; Minnesota Mining and Manufacturing Company, Office of Intellectual Property Counsel, P.O Box 33427, Saint Paul, MN 55133-3427 (US).

(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, GH, HU, IL, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, UZ, VN, YU, ZW, ARIPO patent (GH, KE, LS, MW, SD, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG).

Published
With international search report.

(54) Title: ABRASIVE CONSTRUCTION FOR SEMICONDUCTOR WAFER MODIFICATION



(57) Abstract

An abrasive construction for modifying a surface of a workpiece, such as a semiconductor wafer. The abrasive construction comprises: a three-dimensional, textured, fixed abrasive element; at least one resilient element generally coextensive with the fixed abrasive element; and at least one rigid element generally coextensive with and interposed between the resilient element and the fixed abrasive element, *wherein the rigid element* has a Young's Modulus greater than that of the resilient element.